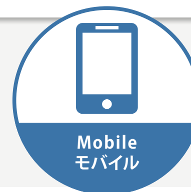
Mass laminations(Shield board)
内層回路入り多層基板材料(シールド板)

PreMulti

Applications 用途

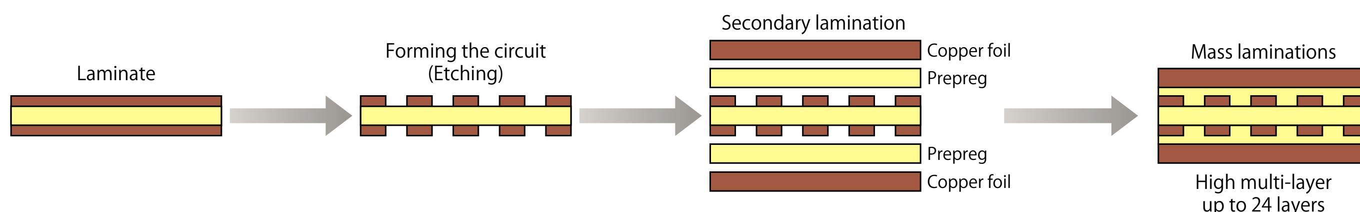
Automotive component, Mobile product, Amusement machine, Digital appliance, Measuring instrument, Semiconductor test equipment, Semiconductor memory board, etc.
車載機器、モバイル機器、アミューズメント機器、デジタル家電、計測機器、半導体試験装置、半導体メモリーボードなど



Reduces the load of customers' circuit formation. Contribute to the impedance matching and crosstalk prevention by increasing flexibility of board design. Quick delivery from order to shipment. Possible to be high multi-layered up to 24 layers.
お客様の回路形成負荷を低減。基板設計の自由度が増し、クロストーク防止やインピーダンス整合に貢献。受注から出荷まで、短納期対応。高多層 24 層まで対応

High multi-layered ~24 layers	AOI inspection for all materials	Quick delivery

What's Mass laminations ? 内層回路入り多層基板材料とは？



Line-up ラインアップ

Product Number	Comment
C-1810	Glass epoxy resin shield board used R-1766 material
C-1510	Halogen-free shield board used R-1566 material
C-1850D	High heat resistance shield board for Automotive component used R-1755D material
C-1850E	Shield board for Automotive component used R-1755E material
C-1850S	High heat resistance shield board for ICT infrastructure equipment used R-1755S material

Specification list 仕様一覧

Item	General Specifications
Board thickness(Max)	2.40mm±10%
Board thickness(Min)	0.24mm±10%
Dimensional tolerance between the reference mark	±0.15mm
Accuracy of the layer reach	0.15mm or less
Warpage	1% or less of the long side
Line/Space	Copper thickness 12μm: 50/50μm
	Copper thickness 18μm: 50/50μm
	Copper thickness 35μm: 75/75μm
	Copper thickness 70μm: 100/100μm
	Copper thickness 105μm: 150/150μm

※The above data is general specifications. Please contact us for more specifications

The above data is actual values and not guaranteed values. 上記データは当社の実測値であり、保証値ではありません。
Please see the page for "Notes before you use" 商品のご採用に当たっての注意事項は こちら

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